

FM340-AHST-Q1 THRU FM3200-AHST-Q1**List**

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings and Electrical characteristics	2
Rating and characteristic curves.....	3
Pinning information.....	4
Marking.....	4
Suggested solder pad layout.....	4
Packing information.....	5
Reel packing.....	6
Suggested thermal profiles for soldering processes.....	6
High reliability test capabilities.....	7

FM340-AHST-Q1 THRU FM3200-AHST-Q1

3.0A Surface Mount Schottky
Barrier Rectifiers 40V-200V

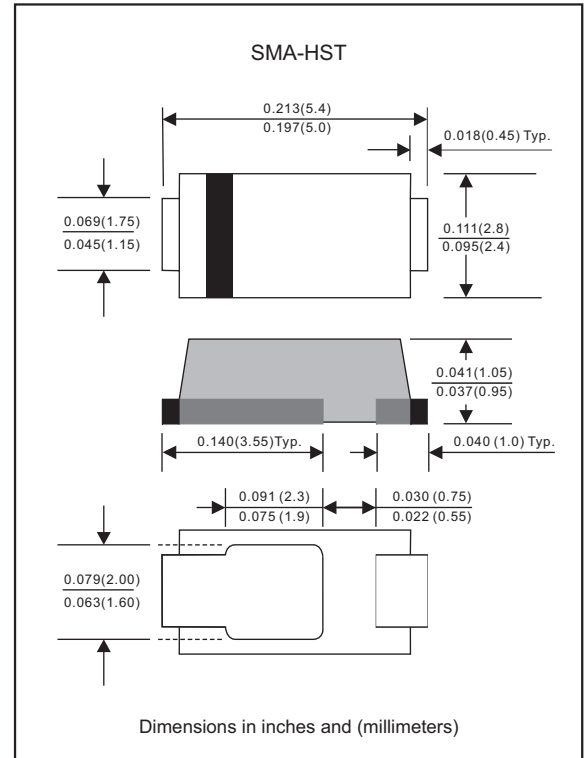
Features

- Well package design with solder pad on the bottom for best thermal performance
- Low profile surface mounted application in order to optimize board space
- Low power loss, high efficiency
- High current capability, low forward voltage drop
- High surge capability
- Guardring for overvoltage protection
- Ultra high-speed switching
- Silicon epitaxial planar chip, metal silicon junction
- Lead-free parts meet RoHS requirements
- Qualified to AEC-Q101 standards for high reliability
- Suffix "-H" indicates Halogen free parts, ex. FM340-AHST-Q1-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic,DO-221BC / SMA-HST
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.037 gram

Package outline

Maximum ratings (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	FM340-AHST-Q1	FM345-AHST-Q1	FM360-AHST-Q1	FM3100-AHST-Q1	FM3150-AHST-Q1	FM3200-AHST-Q1	UNITS
Maximum repetitive peak reverse voltage	VRRM	40	45	60	100	150	200	V
Maximum RMS voltage	VRMS	28	31.5	42	70	105	140	V
Maximum continuous reverse voltage	VR	40	45	60	100	150	200	V
Maximum average forward rectified current	Io	3.0						A
Non-repetitive peak forward surge current 8.3ms single half sine-wave	IFSM	80						A
Typical diode junction capacitance (Note 1)	CJ	250						pF
Operating junction temperature range	TJ	-55 to +125		-55 to +150				°C
Storage temperature range	TSTG	-65 to +175						°C

Electrical characteristics (AT $T_A=25^{\circ}\text{C}$ unless otherwise noted)

PARAMETER	SYMBOLS	FM340-AHST-Q1	FM345-AHST-Q1	FM360-AHST-Q1	FM3100-AHST-Q1	FM3150-AHST-Q1	FM3200-AHST-Q1	UNITS
Maximum instantaneous forward voltage at $I_F=3.0\text{A}$	V_F	0.50	0.50	0.70	0.85	0.90	0.92	V
Maximum reverse leakage current $T_J=25^{\circ}\text{C}$ at rated V_R $T_J=100^{\circ}\text{C}$	I_R	0.5 20						mA mA

Thermal characteristics

PARAMETER	SYMBOLS	FM340-AHST-Q1	FM345-AHST-Q1	FM360-AHST-Q1	FM3100-AHST-Q1	FM3150-AHST-Q1	FM3200-AHST-Q1	UNITS
Typical thermal resistance junction to ambient (Note 2)	$R_{\theta JA}$	46						$^{\circ}\text{C/W}$
Typical thermal resistance junction to case (Note 2)	$R_{\theta JC}$	23						$^{\circ}\text{C/W}$

Notes 1: Measured at 1 MHz and applied reverse voltage of 4.0 VDC

2: Mounted on FR-4 PCB Copper, minimum recommended pad layout



Rating and characteristic curves (FM340-AHST-Q1 THRU FM3200-AHST-Q1)

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

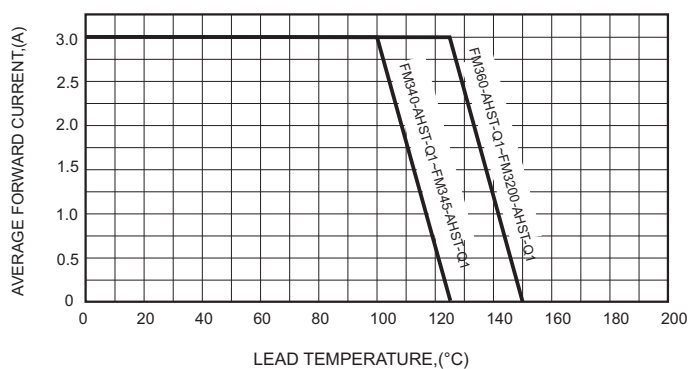


FIG.2-TYPICAL FORWARD CHARACTERISTICS

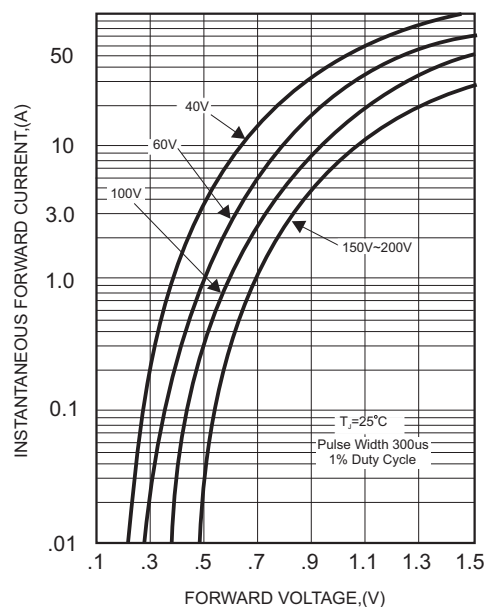


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

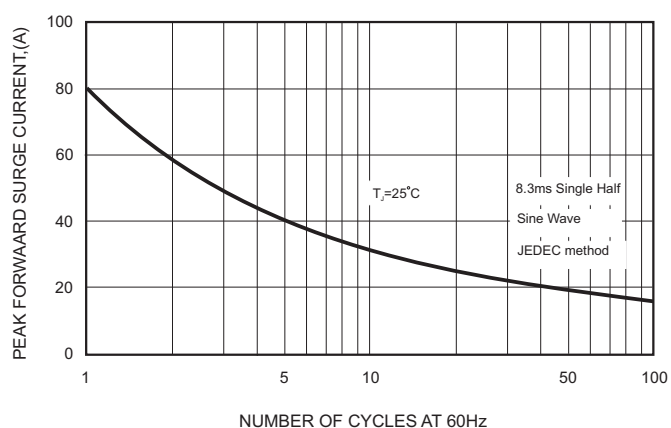


FIG.5 - TYPICAL REVERSE CHARACTERISTICS

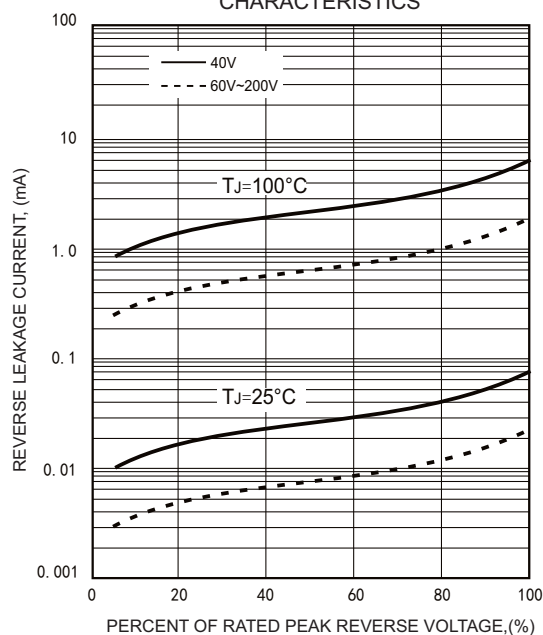
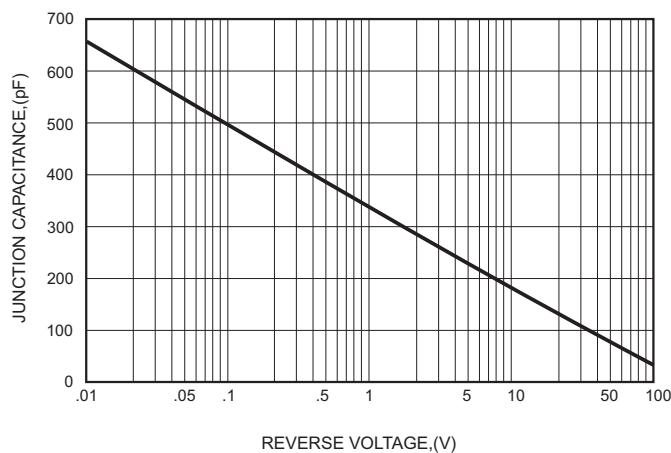


FIG.4-TYPICAL JUNCTION CAPACITANCE

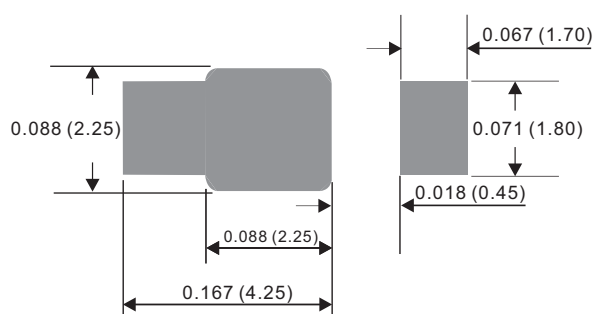


FM340-AHST-Q1 THRU FM3200-AHST-Q1**Pinning information**

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

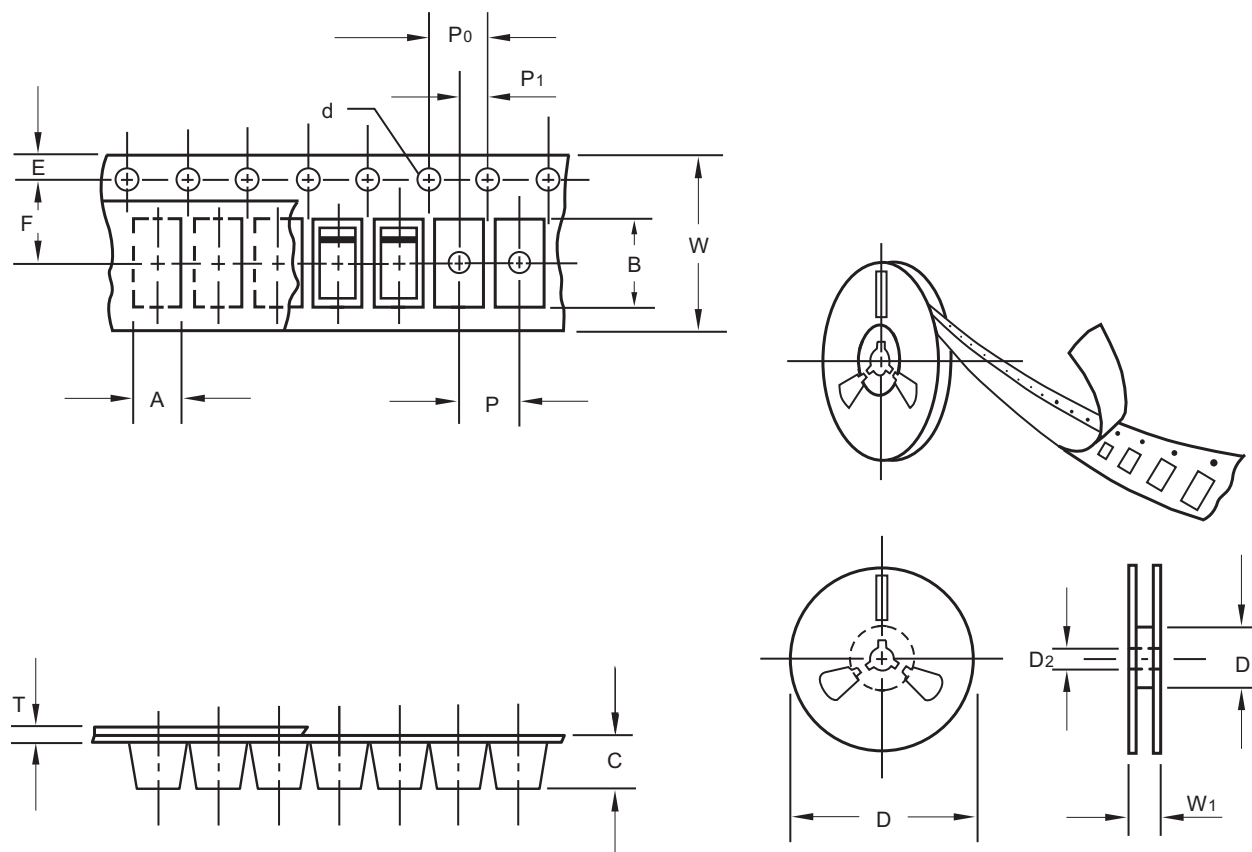
Marking

Type number	Marking code
FM340-AHST-Q1	SK34
FM345-AHST-Q1	SK34
FM360-AHST-Q1	SK36
FM3100-AHST-Q1	S310
FM3150-AHST-Q1	S315
FM3200-AHST-Q1	S320

Suggested solder pad layout

Dimensions in inches and (millimeters)

Packing information



unit:mm

Item	Symbol	Tolerance	SMA-HST
Carrier width	A	0.1	3.00
Carrier length	B	0.1	5.50
Carrier depth	C	0.1	1.20
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	330.00
13" Reel inner diameter	D1	min	50.00
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	62.00
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	5.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.25
Tape width	W	0.3	12.00
Reel width	W1	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

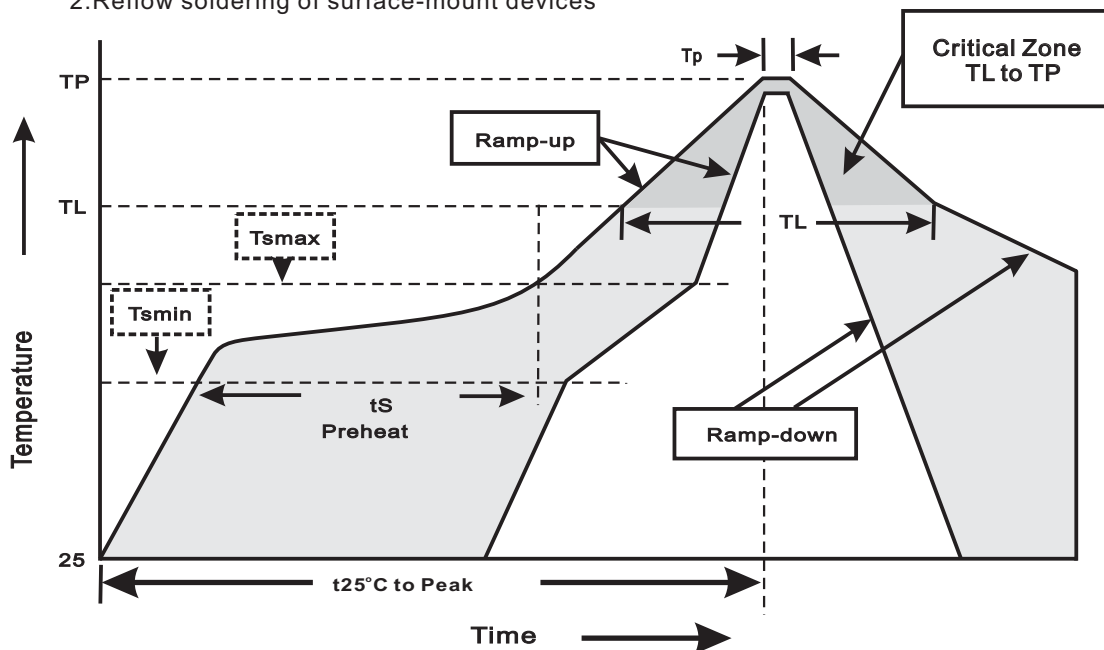
FM340-AHST-Q1 THRU FM3200-AHST-Q1

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SMA-HST	7"	3,000	4.0	30,000	183*155*183	178	382*356*392	240,000	18.0
	13"	10,000	4.0	20,000	335*335*38	330	350*330*360	160,000	15.5

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T _L to T _P)	<3°C/sec
Preheat -Temperature Min(T _{smmin}) -Temperature Max(T _{smmax}) -Time(min to max)(t _s)	150°C 200°C 60~120sec
T _{smmax} to T _L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T _L) -Time(t _L)	217°C 60~260sec
Peak Temperature(T _P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t _P)	10~30sec
Ramp-down Rate	<3°C/sec
Time 25°C to Peak Temperature	<6minutes

FM340-AHST-Q1 THRU FM3200-AHST-Q1**High reliability test capabilities**

Item Test	Conditions	Reference
1. MSL Preconditioning	24hr bake@125°C+168hrs@85°C /85%RH+3xIR@260°C+1flux immersion+alcohol+DI H2O rinse	JESD22-A113
2. Operation Life	Ta=25°C,Rated Current (Io=Io max.)Test Duration:1000hrs	MIL-STD-750E METHOD 1027.3
3. High Temperature Reverse Bias	80% Rated VR (Tj=Tj max.)Test Duration:1000hrs	JESD22-A108
4. High Temperature Storage Life	Ta=125°C Test Duration:1000hrs	JESD22 A-103
5. Temperature Cycle	-55°C(15min) to 150°C(15min)Test Cycles:1000cycles	JESD22 A-104
6. Autoclave	P=2atm Ta=121°C RH=100% Test Duration:96hrs	JESD22 A-102
7. Intermittent Operational Life	Ta=25°C,On/Io Max. 2min, Off/2min, Test Cycles:15000cycles	MIL-STD-750E METHOD 1037
8. Solderability	245±5°C for 5sec	J-STD-002
9. Moisture Resistance	Ta=85°C/85% Relative humidity Test Duration:1000hrs	MIL-STD-750E METHOD 1021.2
10. Resistance To Solder Heat	260±5°C for 10sec	JESD22 B-106
11. High Temperature High Humidity Reverse Bias	Ta=85°C, 85%RH, with device reverse biased at 80% of rated breakdown voltage up to a maximum of 100V or limit of chamber Test Duration:1000hrs	JESD22-A101